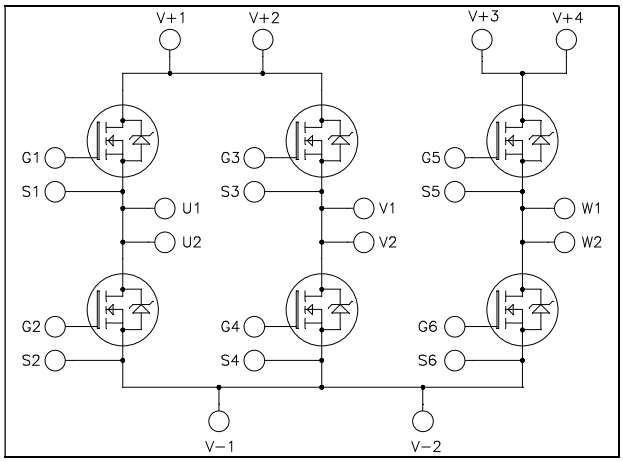
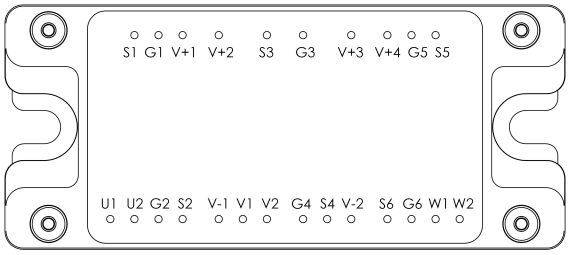
MSCM20XM16F4G

3 phase bridge MOSFET Power Module

V_{DSS} = 200V
R_{DSon} = 16mΩ typ @ Tj = 25°C
I_D = 104A* @ Tc = 25°C





Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Power MOS 7® FREDFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Fast intrinsic reverse diode
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

All ratings @ T_j = 25°C unless otherwise specified

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		200	V
I_D	Continuous Drain Current	T_c = 25°C	104*	A
		T_c = 80°C	77*	
I_{DM}	Pulsed Drain current		416	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		19	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	390	W
I_{AR}	Avalanche current (repetitive and non repetitive)		104	A
E_{AR}	Repetitive Avalanche Energy		50	mJ
E_{AS}	Single Pulse Avalanche Energy		3000	

* Specification of device but output current must be limited due to connectors' temperature.

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V, V_{DS} = 200V	T_j = 25°C			250	µA
		V_{GS} = 0V, V_{DS} = 160V	T_j = 125°C			1000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 52A			16	19	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 2.5mA		3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V				±140	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		7220		pF
C_{oss}	Output Capacitance			2330		
C_{rss}	Reverse Transfer Capacitance			146		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 100V I_D =104A		140		nC
Q_{gs}	Gate – Source Charge			53		
Q_{gd}	Gate – Drain Charge			67		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 133V I_D = 104A R_G = 5Ω		32		ns
T_r	Rise Time			64		
$T_{d(off)}$	Turn-off Delay Time			88		
T_f	Fall Time			116		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 133V I_D = 104A, R_G = 5Ω		936		µJ
E_{off}	Turn-off Switching Energy			986		
R_{thJC}	Junction to Case Thermal Resistance				0.33	°C/W

Source - Drain diode ratings and characteristics

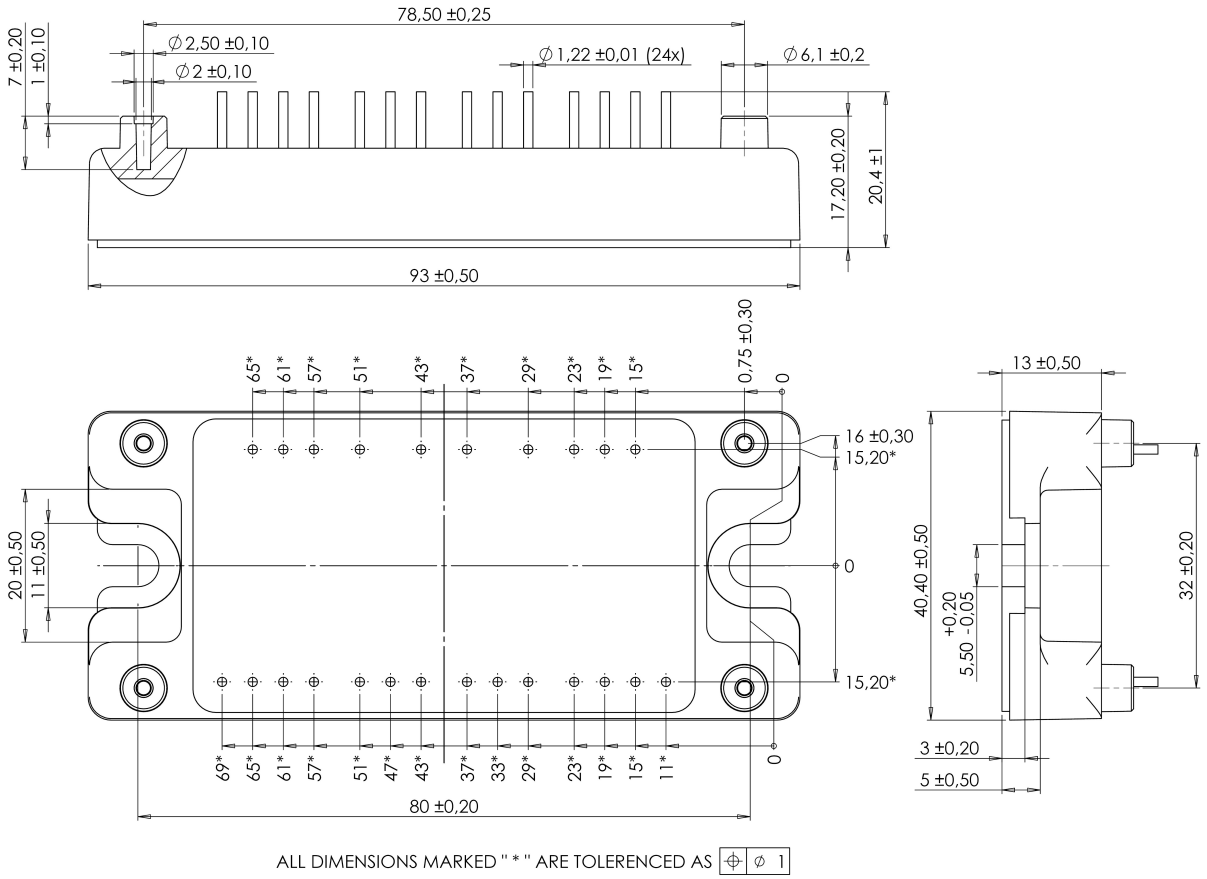
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_S	Continuous Source current (Body diode)		Tc = 25°C			104	A
			Tc = 80°C			77	
V_{SD}	Diode Forward Voltage	V_{GS} = 0V, I_S = - 104A				1.3	V
dv/dt	Peak Diode Recovery ❶					5	V/ns
t_{rr}	Reverse Recovery Time	I_S = - 104A V_R = 133V di_S/dt = 100A/µs	T_j = 25°C			230	ns
			T_j = 125°C			450	
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		0.9		µC
			T_j = 125°C		3.4		

❶ dv/dt numbers reflect the limitations of the circuit rather than the device itself.
$I_S \le$ - 104A di/dt ≤ 700A/µs $V_R \le V_{DSS}$ $T_j \le$ 150°C

Thermal and package characteristics

Symbol	*Characteristic*			*Min*	*Max*	*Unit*
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000		V
T_J	Operating junction temperature range			-40	150	°C
T_{JOP}	Recommended junction temperature under switching conditions			-40	$T_J$max -25	
T_{STG}	Storage Temperature Range			-40	125	
T_C	Operating Case Temperature			-40	125	
Torque	Mounting torque	To Heatsink	M5	2.5	4.7	N.m
Wt	Package Weight				160	g

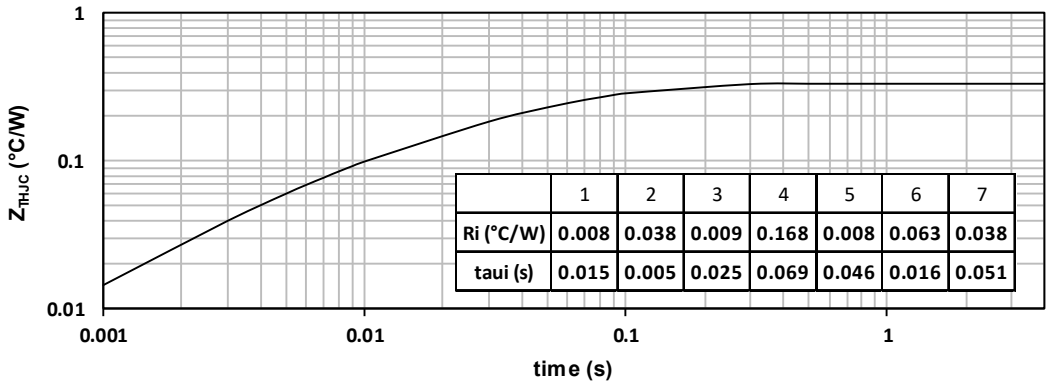
Package outline (dimensions in mm)



See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

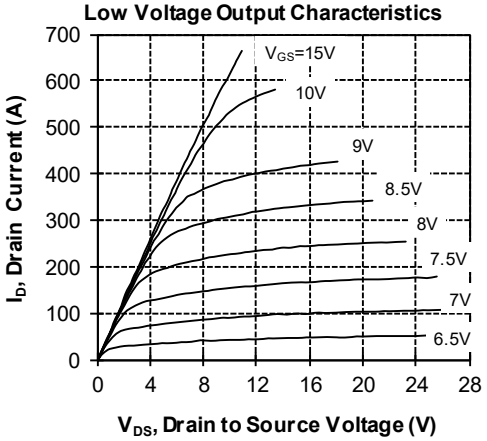
Typical Performance Curve

Maximum thermal impedance

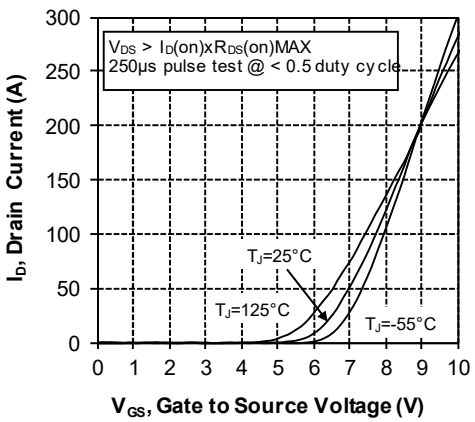


	1	2	3	4	5	6	7
Ri (°C/W)	0.008	0.038	0.009	0.168	0.008	0.063	0.038
taui (s)	0.015	0.005	0.025	0.069	0.046	0.016	0.051

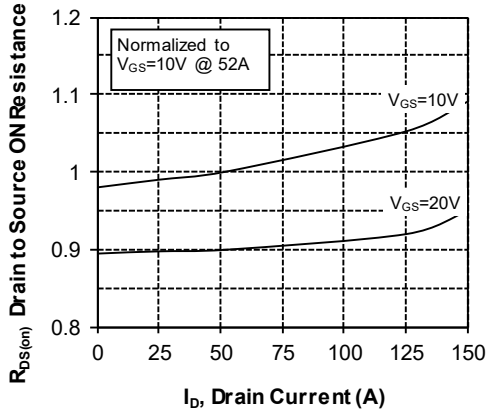
Low Voltage Output Characteristics



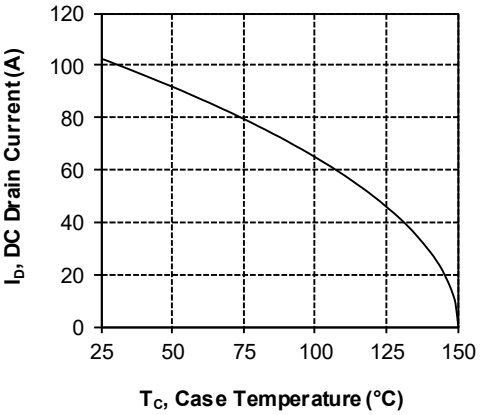
Transfert Characteristics

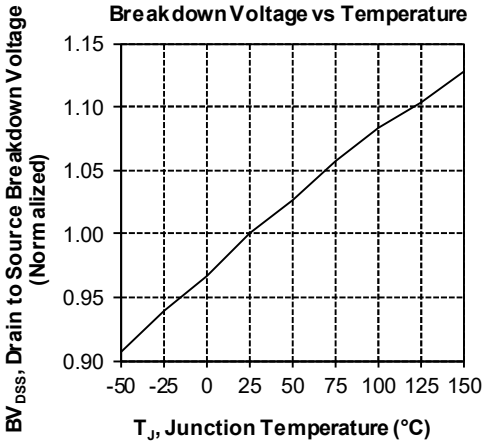


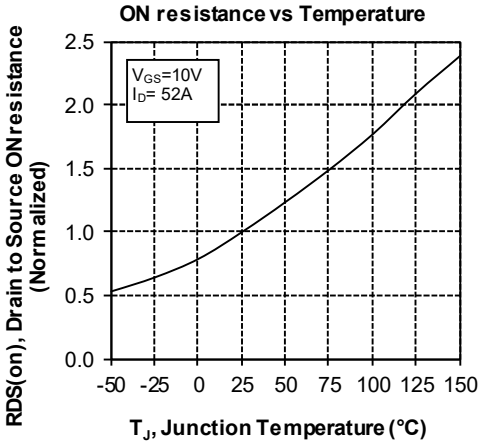
$R_{DS(on)}$ vs Drain Current

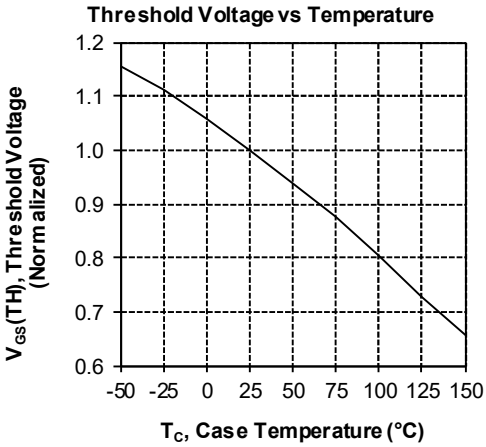


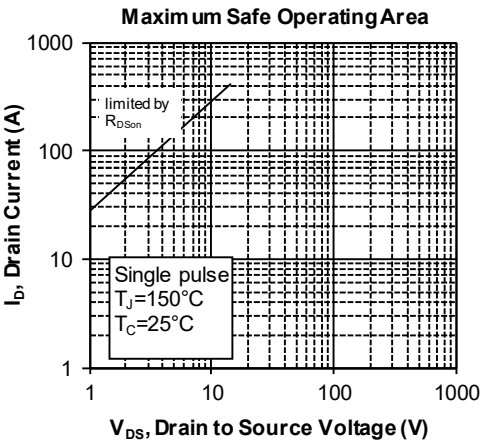
DC Drain Current vs Case Temperature

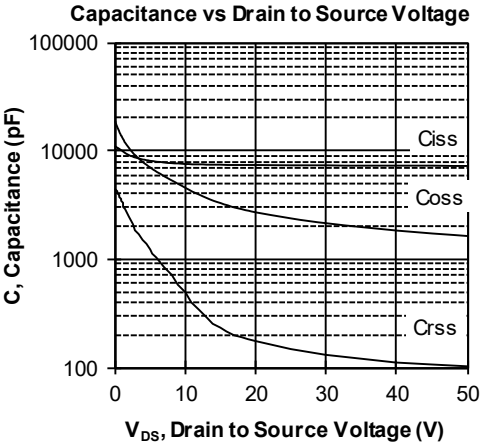


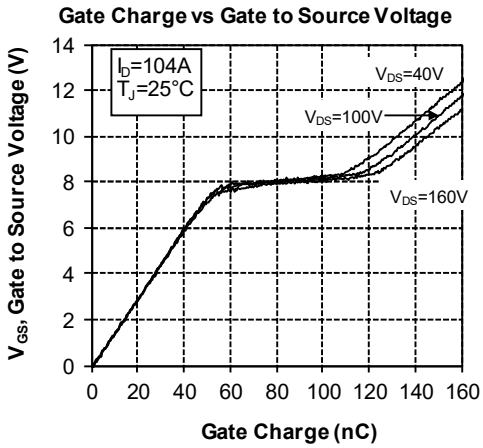

Breakdown Voltage vs Temperature
BVDSS, Drain to Source Breakdown Voltage (Normalized)
1.15
1.10
1.05
1.00
0.95
0.90
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)


ON resistance vs Temperature
RDS(on), Drain to Source ONresistance (Normalized)
VGS=10V
ID= 52A
2.5
2.0
1.5
1.0
0.5
0.0
-50 -25 0 25 50 75 100 125 150
TJ, Junction Temperature (°C)

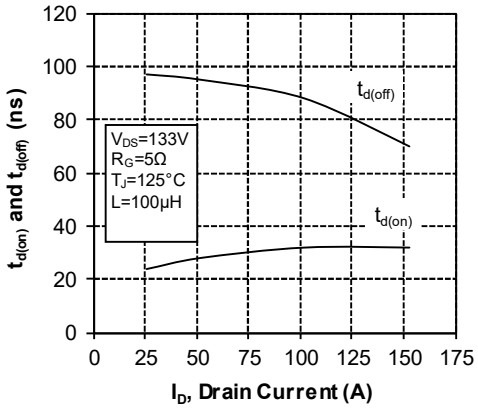

Threshold Voltage vs Temperature
VGS(TH), Threshold Voltage (Normalized)
1.2
1.1
1.0
0.9
0.8
0.7
0.6
-50 -25 0 25 50 75 100 125 150
TC, Case Temperature (°C)


Maximum Safe Operating Area
ID, Drain Current (A)
1000
100
10
1
limited by RDSon
Single pulse
TJ=150°C
TC=25°C
1
10
100
1000
VDS, Drain to Source Voltage (V)

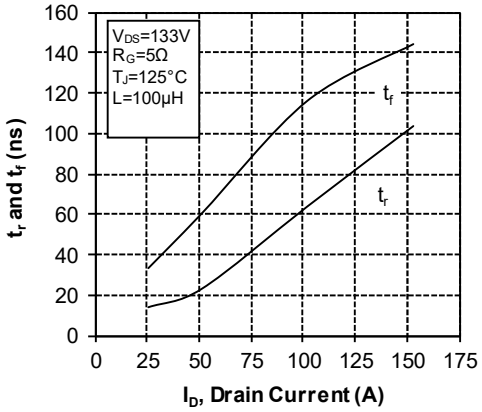

Capacitance vs Drain to Source Voltage
C, Capacitance (pF)
100000
10000
1000
100
Ciss
Coss
Crss
0 10 20 30 40 50
VDS, Drain to Source Voltage (V)


Gate Charge vs Gate to Source Voltage
VGS, Gate to Source Voltage (V)
ID=104A
TJ=25°C
VDS=40V
VDS=100V
VDS=160V
14
12
10
8
6
4
2
0
0 20 40 60 80 100 120 140 160
Gate Charge (nC)

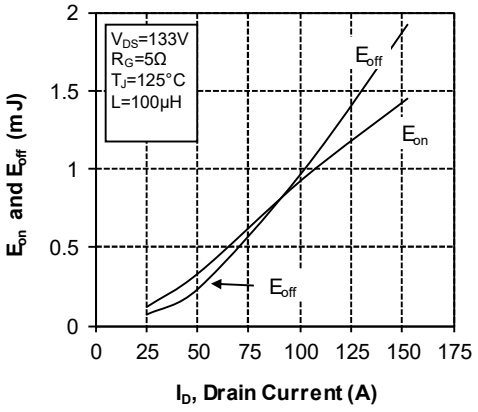
Delay Times vs Current



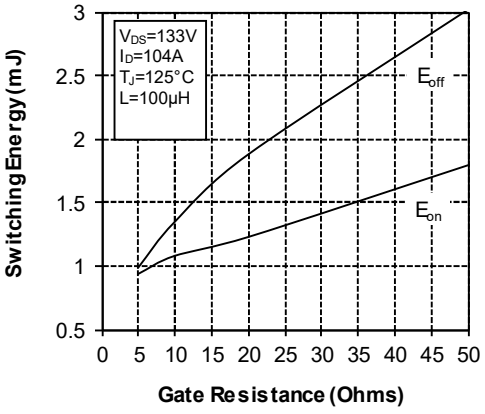
Rise and Fall times vs Current



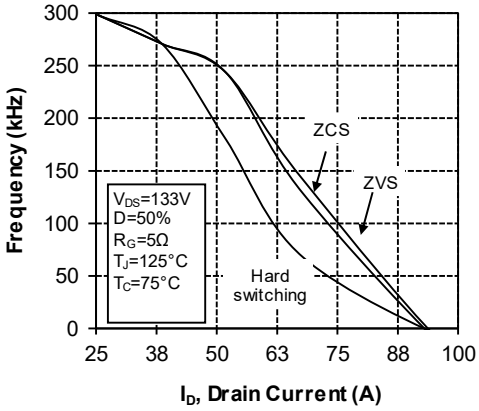
Switching Energy vs Current



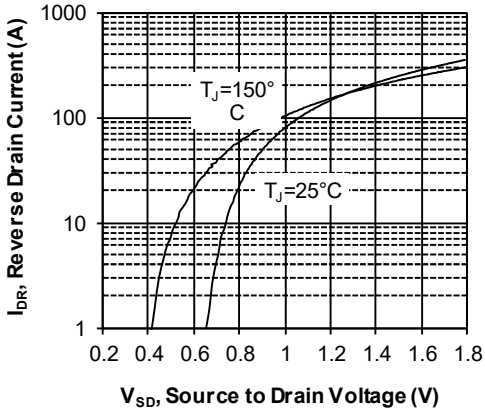
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



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